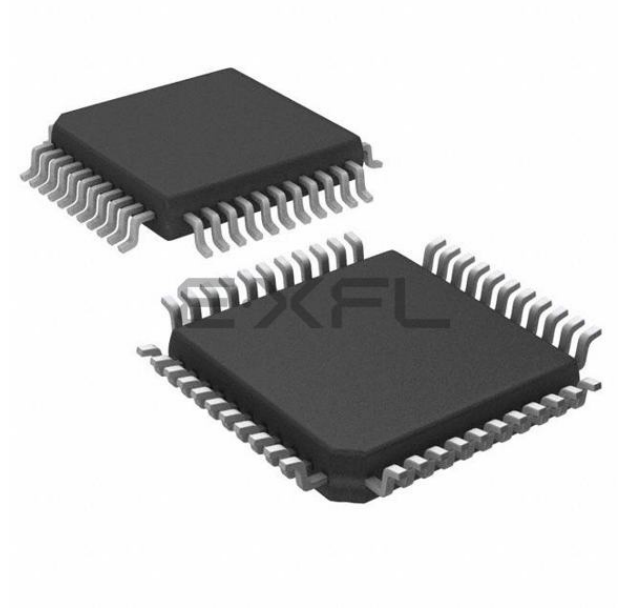

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c44t-16i-pq

TABLE 1-1: PIC17CXX FAMILY OF DEVICES

Features		PIC17C42	PIC17CR42	PIC17C42A	PIC17C43	PIC17CR43	PIC17C44
Maximum Frequency of Operation		25 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz
Operating Voltage Range		4.5 - 5.5V	2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V
Program Memory x16	(EPROM)	2K	-	2K	4K	-	8K
	(ROM)	-	2K	-	-	4K	-
Data Memory (bytes)		232	232	232	454	454	454
Hardware Multiplier (8 x 8)		-	Yes	Yes	Yes	Yes	Yes
Timer0 (16-bit + 8-bit postscaler)		Yes	Yes	Yes	Yes	Yes	Yes
Timer1 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes
Timer2 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes
Timer3 (16-bit)		Yes	Yes	Yes	Yes	Yes	Yes
Capture inputs (16-bit)		2	2	2	2	2	2
PWM outputs (up to 10-bit)		2	2	2	2	2	2
USART/SCI		Yes	Yes	Yes	Yes	Yes	Yes
Power-on Reset		Yes	Yes	Yes	Yes	Yes	Yes
Watchdog Timer		Yes	Yes	Yes	Yes	Yes	Yes
External Interrupts		Yes	Yes	Yes	Yes	Yes	Yes
Interrupt Sources		11	11	11	11	11	11
Program Memory Code Protect		Yes	Yes	Yes	Yes	Yes	Yes
I/O Pins		33	33	33	33	33	33
I/O High Current Capability	Source	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA
	Sink	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)
Package Types		40-pin DIP 44-pin PLCC 44-pin MQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP

Note 1: Pins RA2 and RA3 can sink up to 60 mA.

TABLE 3-1: PINOUT DESCRIPTIONS

Name	DIP No.	PLCC No.	QFP No.	I/O/P Type	Buffer Type	Description
						PORTD is a bi-directional I/O Port.
RD0/AD8	40	43	15	I/O	TTL	This is also the upper byte of the 16-bit system bus in microprocessor mode or extended microprocessor mode or extended microcontroller mode. In multiplexed system bus configuration these pins are address output as well as data input or output.
RD1/AD9	39	42	14	I/O	TTL	
RD2/AD10	38	41	13	I/O	TTL	
RD3/AD11	37	40	12	I/O	TTL	
RD4/AD12	36	39	11	I/O	TTL	
RD5/AD13	35	38	10	I/O	TTL	
RD6/AD14	34	37	9	I/O	TTL	
RD7/AD15	33	36	8	I/O	TTL	
						PORTE is a bi-directional I/O Port.
RE0/ALE	30	32	4	I/O	TTL	In microprocessor mode or extended microcontroller mode, it is the Address Latch Enable (ALE) output. Address should be latched on the falling edge of ALE output.
RE1/$\overline{OE}$	29	31	3	I/O	TTL	In microprocessor or extended microcontroller mode, it is the Output Enable ($\overline{OE}$) control output (active low).
RE2/$\overline{WR}$	28	30	2	I/O	TTL	In microprocessor or extended microcontroller mode, it is the Write Enable ($\overline{WR}$) control output (active low).
TEST	27	29	1	I	ST	Test mode selection control input. Always tie to VSS for normal operation.
VSS	10, 31	11, 12, 33, 34	5, 6, 27, 28	P		Ground reference for logic and I/O pins.
VDD	1	1, 44	16, 17	P		Positive supply for logic and I/O pins.

Legend: I = Input only; O = Output only; I/O = Input/Output; P = Power; — = Not Used; TTL = TTL input; ST = Schmitt Trigger input.

6.3 Stack Operation

The PIC17C4X devices have a 16 x 16-bit wide hardware stack (Figure 6-1). The stack is not part of either the program or data memory space, and the stack pointer is neither readable nor writable. The PC is "PUSHed" onto the stack when a CALL instruction is executed or an interrupt is acknowledged. The stack is "POPed" in the event of a RETURN, RETLW, or a RETFIE instruction execution. PCLATH is not affected by a "PUSH" or a "POP" operation.

The stack operates as a circular buffer, with the stack pointer initialized to '0' after all resets. There is a stack available bit (STKAV) to allow software to ensure that the stack has not overflowed. The STKAV bit is set after a device reset. When the stack pointer equals Fh, STKAV is cleared. When the stack pointer rolls over from Fh to 0h, the STKAV bit will be held clear until a device reset.

Note 1: There is not a status bit for stack underflow. The STKAV bit can be used to detect the underflow which results in the stack pointer being at the top of stack.

Note 2: There are no instruction mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW, and RETFIE instructions, or the vectoring to an interrupt vector.

Note 3: After a reset, if a "POP" operation occurs before a "PUSH" operation, the STKAV bit will be cleared. This will appear as if the stack is full (underflow has occurred). If a "PUSH" operation occurs next (before another "POP"), the STKAV bit will be locked clear. Only a device reset will cause this bit to set.

After the device is "PUSHed" sixteen times (without a "POP"), the seventeenth push overwrites the value from the first push. The eighteenth push overwrites the second push (and so on).

6.4 Indirect Addressing

Indirect addressing is a mode of addressing data memory where the data memory address in the instruction is not fixed. That is, the register that is to be read or written can be modified by the program. This can be useful for data tables in the data memory. Figure 6-10 shows the operation of indirect addressing. This shows the moving of the value to the data memory address specified by the value of the FSR register.

Example 6-1 shows the use of indirect addressing to clear RAM in a minimum number of instructions. A similar concept could be used to move a defined number of bytes (block) of data to the USART transmit register (TXREG). The starting address of the block of data to be transmitted could easily be modified by the program.

FIGURE 6-10: INDIRECT ADDRESSING

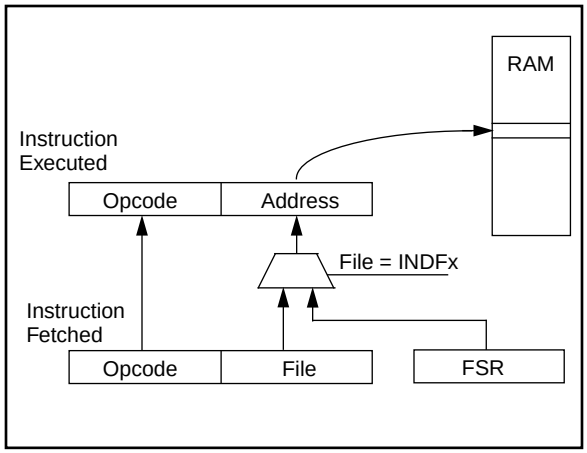
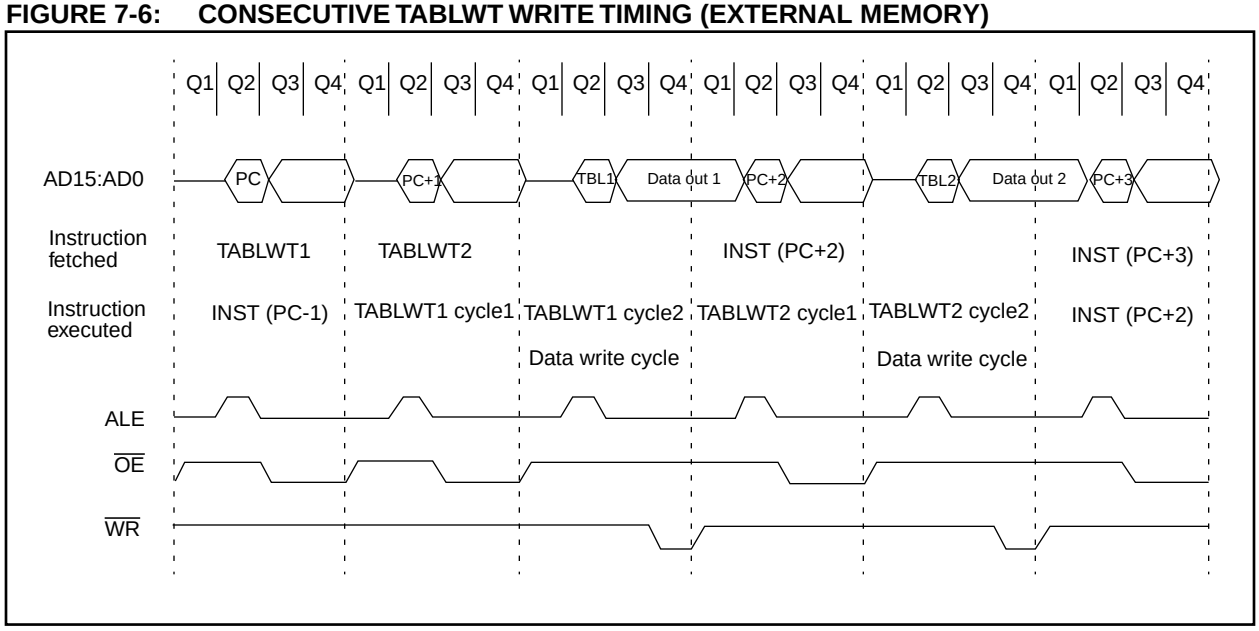


FIGURE 7-6: CONSECUTIVE TABLWT WRITE TIMING (EXTERNAL MEMORY)



9.2 PORTB and DDRB Registers

PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is DDRB. A '1' in DDRB configures the corresponding port pin as an input. A '0' in the DDRB register configures the corresponding port pin as an output. Reading PORTB reads the status of the pins, whereas writing to it will write to the port latch.

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is done by clearing the $\overline{\text{RBPU}}$ (PORTA<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are enabled on any reset.

PORTB also has an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e. any RB7:RB0 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB0) are compared with the value in the PORTB data latch. The "mismatch" outputs of RB7:RB0 are OR'ed together to generate the PORTB Interrupt Flag RBIF (PIR<7>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt by:

a) Read-Write PORTB (such as; `MOVPF PORTB, PORTB`). This will end mismatch condition.

b) Then, clear the RBIF bit.

A mismatch condition will continue to set the RBIF bit. Reading then writing PORTB will end the mismatch condition, and allow the RBIF bit to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on this port, allows easy interface to a key pad and make it possible for wake-up on key-depression. For an example, refer to AN552 in the *Embedded Control Handbook*.

The interrupt on change feature is recommended for wake-up on operations where PORTB is only used for the interrupt on change feature and key depression operation.

FIGURE 9-4: BLOCK DIAGRAM OF RB<7:4> AND RB<1:0> PORT PINS

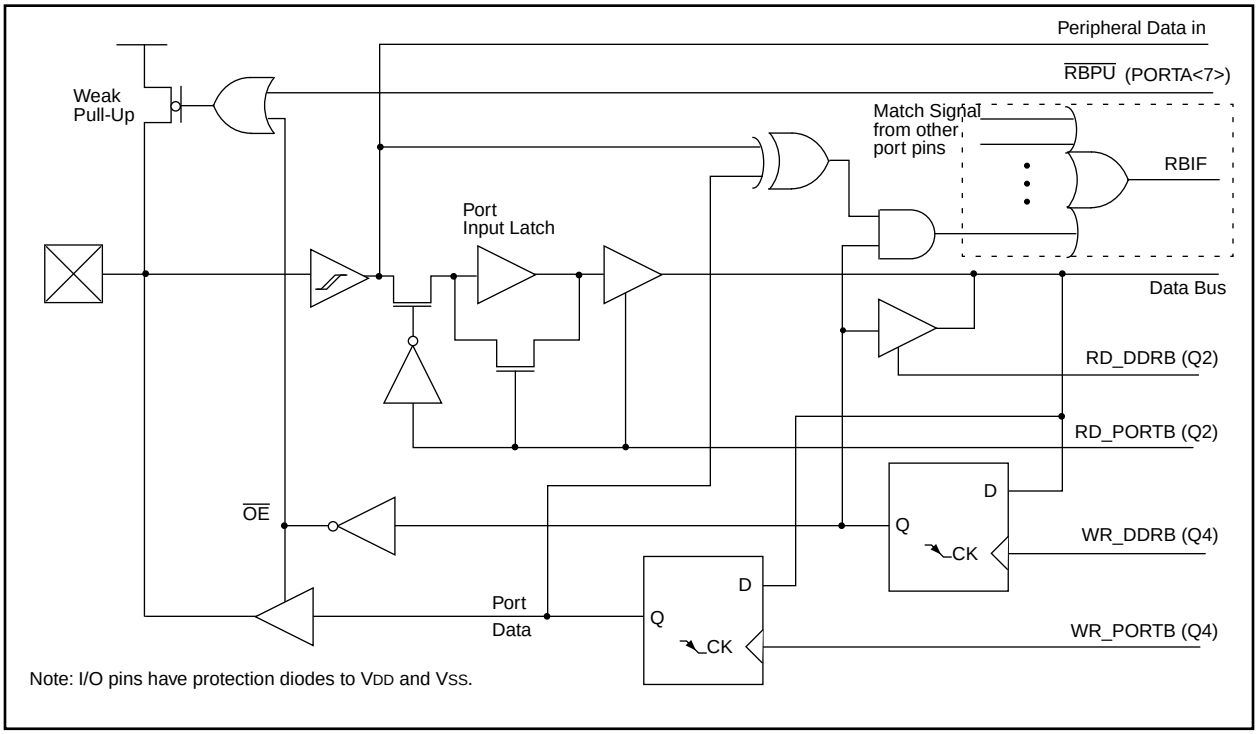


FIGURE 12-10: TMR1, TMR2, AND TMR3 OPERATION IN TIMER MODE

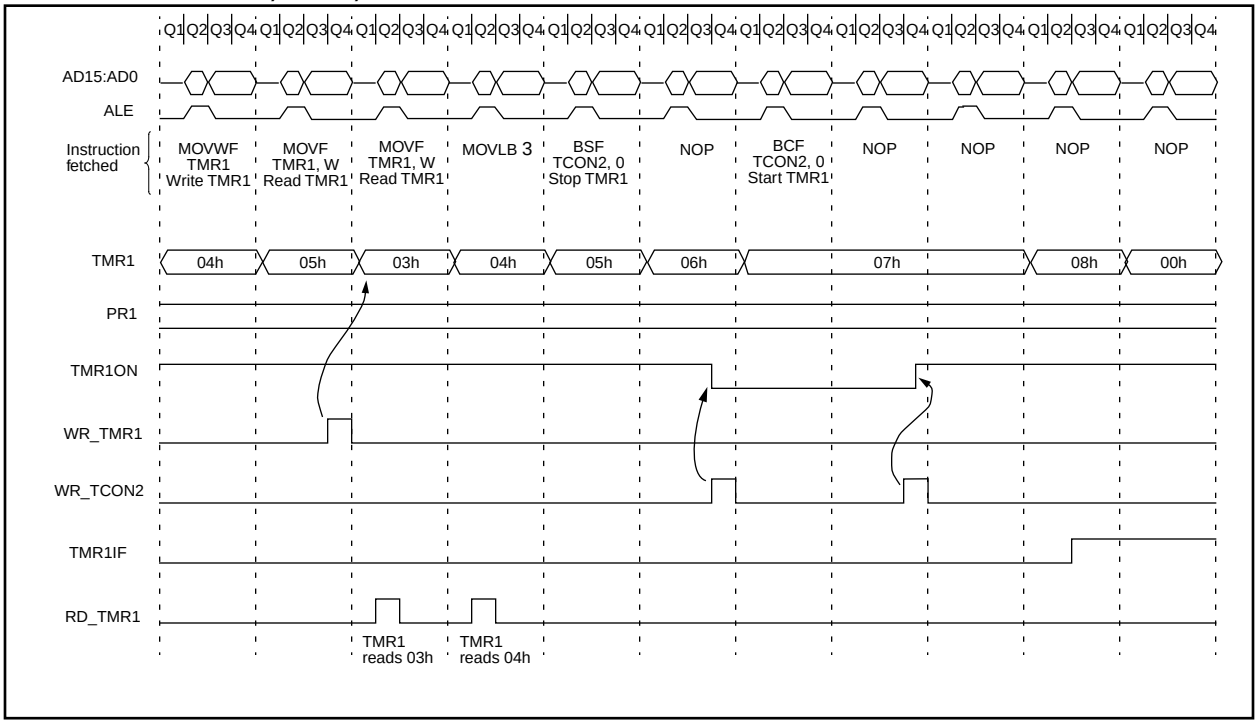


TABLE 12-6: SUMMARY OF TMR1, TMR2, AND TMR3 REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 3	TCON1	CA2ED1	CA2ED0	CA1ED1	CA1ED0	T16	TMR3CS	TMR2CS	TMR1CS	0000 0000	0000 0000
17h, Bank 3	TCON2	CA2OVF	CA1OVF	PWM2ON	PWM1ON	CA1/$\overline{PR3}$	TMR3ON	TMR2ON	TMR1ON	0000 0000	0000 0000
10h, Bank 2	TMR1	Timer1 register								xxxx xxxx	uuuu uuuu
11h, Bank 2	TMR2	Timer2 register								xxxx xxxx	uuuu uuuu
12h, Bank 2	TMR3L	TMR3 register; low byte								xxxx xxxx	uuuu uuuu
13h, Bank 2	TMR3H	TMR3 register; high byte								xxxx xxxx	uuuu uuuu
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
07h, Unbanked	INTSTA	PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
06h, Unbanked	CPUSTA	—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	—	—	--11 11--	--11 qq--
14h, Bank 2	PR1	Timer1 period register								xxxx xxxx	uuuu uuuu
15h, Bank 2	PR2	Timer2 period register								xxxx xxxx	uuuu uuuu
16h, Bank 2	PR3L/CA1L	Timer3 period/capture1 register; low byte								xxxx xxxx	uuuu uuuu
17h, Bank 2	PR3H/CA1H	Timer3 period/capture1 register; high byte								xxxx xxxx	uuuu uuuu
10h, Bank 3	PW1DCL	DC1	DC0	—	—	—	—	—	—	xx-- ----	uu-- ----
11h, Bank 3	PW2DCL	DC1	DC0	TM2PW2	—	—	—	—	—	xx0- ----	uu0- ----
12h, Bank 3	PW1DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu
13h, Bank 3	PW2DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu
14h, Bank 3	CA2L	Capture2 low byte								xxxx xxxx	uuuu uuuu
15h, Bank 3	CA2H	Capture2 high byte								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as '0', q - value depends on condition, shaded cells are not used by TMR1, TMR2 or TMR3.

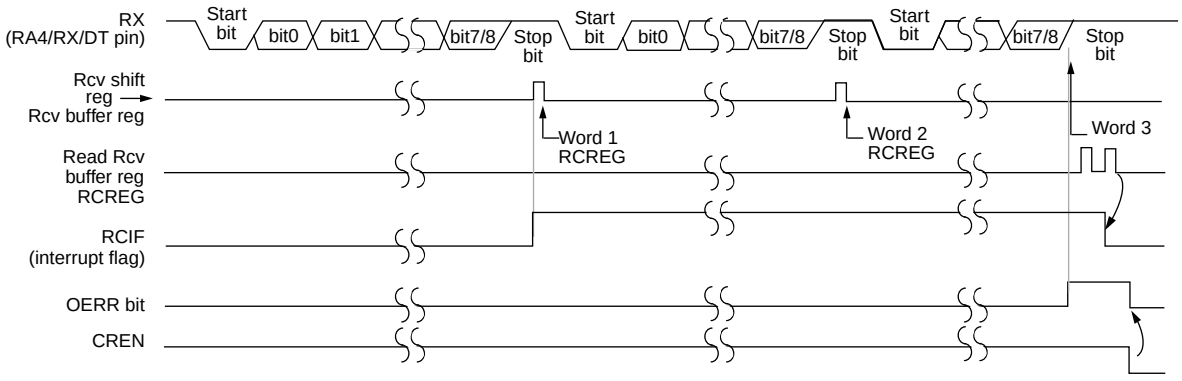
Note 1: Other (non power-up) resets include: external reset through $\overline{MCLR}$ and WDT Timer Reset.

Steps to follow when setting up an Asynchronous Reception:

1. Initialize the SPBRG register for the appropriate baud rate.
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If interrupts are desired, then set the RCIE bit.
4. If 9-bit reception is desired, then set the RX9 bit.
5. Enable the reception by setting the CREN bit.
6. The RCIF bit will be set when reception completes and an interrupt will be generated if the RCIE bit was set.
7. Read RCSTA to get the ninth bit (if enabled) and FERR bit to determine if any error occurred during reception.
8. Read RCREG for the 8-bit received data.
9. If an overrun error occurred, clear the error by clearing the OERR bit.

Note: To terminate a reception, either clear the SREN and CREN bits, or the SPEN bit. This will reset the receive logic, so that it will be in the proper state when receive is re-enabled.

FIGURE 13-8: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

TABLE 13-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
13h, Bank 0	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00u
14h, Bank 0	RCREG	RX7	RX6	RX5	RX4	RX3	RX2	RX1	RX0	xxxx xxxx	uuuu uuuu
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
15h, Bank 0	TXSTA	CSRC	TX9	TXEN	SYNC	—	—	TRMT	TX9D	0000 --1x	0000 --1u
17h, Bank 0	SPBRG	Baud rate generator register								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', shaded cells are not used for asynchronous reception.
Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and Watchdog Timer Reset.

13.3.2 USART SYNCHRONOUS MASTER RECEPTION

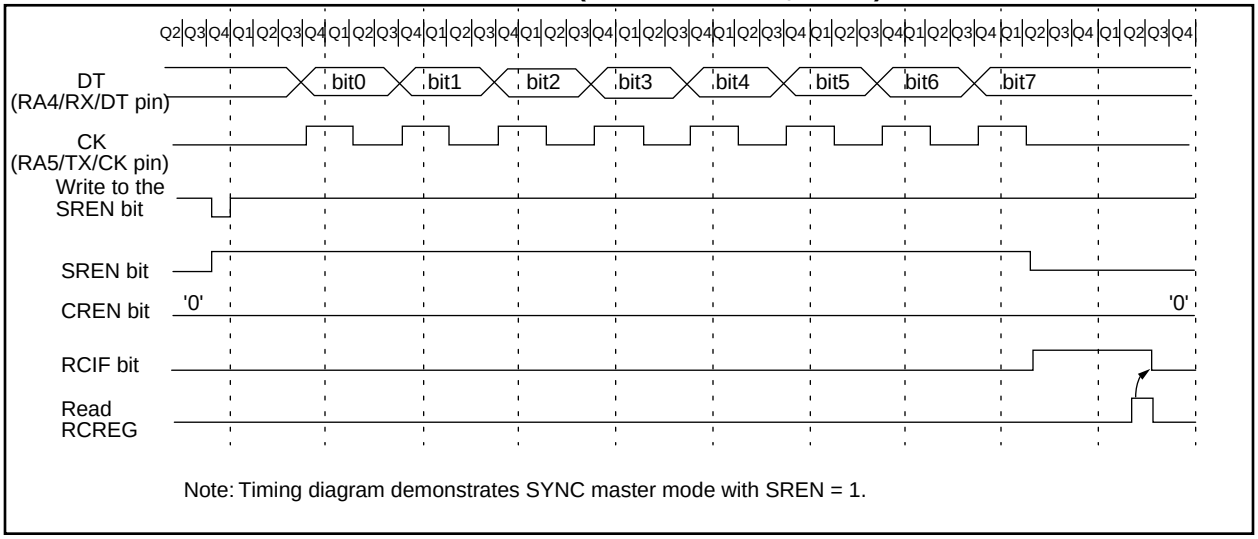
Once synchronous mode is selected, reception is enabled by setting either the SREN (RCSTA<5>) bit or the CREN (RCSTA<4>) bit. Data is sampled on the RA4/RX/DT pin on the falling edge of the clock. If SREN is set, then only a single word is received. If CREN is set, the reception is continuous until CREN is reset. If both bits are set, then CREN takes precedence. After clocking the last bit, the received data in the Receive Shift Register (RSR) is transferred to RCREG (if it is empty). If the transfer is complete, the interrupt bit RCIF (PIR<0>) is set. The actual interrupt can be enabled/disabled by setting/clearing the RCIE (PIE<0>) bit. RCIF is a read only bit which is RESET by the hardware. In this case it is reset when RCREG has been read and is empty. RCREG is a double buffered register; i.e., it is a two deep FIFO. It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting into the RSR. On the clocking of the last bit of the third byte, if RCREG is still full, then the overrun error bit OERR (RCSTA<1>) is set. The word in the RSR will be lost. RCREG can be read twice to retrieve the two bytes in the FIFO. The OERR bit has to be cleared in software. This is done by clearing the CREN bit. If OERR bit is set, transfers from RSR to RCREG are inhibited, so it is essential to clear OERR bit if it is set. The 9th receive bit is buffered the same way as the receive data. Reading the RCREG register will allow the RX9D and FERR bits to be loaded with values for the next received data; therefore, it is essential for the user to read the RCSTA register before reading RCREG in order not to lose the old FERR and RX9D information.

Steps to follow when setting up a Synchronous Master Reception:

1. Initialize the SPBRG register for the appropriate baud rate. See Section 13.1 for details.
2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
3. If interrupts are desired, then set the RCIE bit.
4. If 9-bit reception is desired, then set the RX9 bit.
5. If a single reception is required, set bit SREN. For continuous reception set bit CREN.
6. The RCIF bit will be set when reception is complete and an interrupt will be generated if the RCIE bit was set.
7. Read RCSTA to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading RCREG.
9. If any error occurred, clear the error by clearing CREN.

Note:	To terminate a reception, either clear the SREN and CREN bits, or the SPEN bit. This will reset the receive logic, so that it will be in the proper state when receive is re-enabled.

FIGURE 13-11: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates SYNC master mode with SREN = 1.

ADDWFC **ADD WREG and Carry bit to f**

Syntax: [*label*] ADDWFC f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (WREG) + (f) + C → (dest)

Status Affected: OV, C, DC, Z

Encoding:

0001	000d	ffff	ffff

Description: Add WREG, the Carry Flag and data memory location 'f'. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is placed in data memory location 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: `ADDWFC REG 0`

Before Instruction
Carry bit = 1
REG = 0x02
WREG = 0x4D

After Instruction
Carry bit = 0
REG = 0x02
WREG = 0x50

ANDLW **And Literal with WREG**

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (WREG) .AND. (k) → (WREG)

Status Affected: Z

Encoding:

1011	0101	kkkk	kkkk

Description: The contents of WREG are AND'ed with the 8-bit literal 'k'. The result is placed in WREG.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Execute	Write to WREG

Example: `ANDLW 0x5F`

Before Instruction
WREG = 0xA3

After Instruction
WREG = 0x03

CPFSLT — **Compare f with WREG, skip if f < WREG**

Syntax: [*label*] CPFSLT f

Operands: $0 \le f \le 255$

Operation: (f) – (WREG), skip if (f) < (WREG) (unsigned comparison)

Status Affected: None

Encoding:

0011	0000	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of WREG by performing an unsigned subtraction.

If the contents of 'f' < the contents of WREG, then the fetched instruction is discarded and an NOP is executed instead making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	NOP

If skip:

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

Example:

```
HERE    CPFSLT REG
NLESS   :
LESS    :
```

Before Instruction
PC = Address (HERE)
W = ?

After Instruction
If REG < WREG;
PC = Address (LESS)
If REG ≥ WREG;
PC = Address (NLESS)

DAW — **Decimal Adjust WREG Register**

Syntax: [*label*] DAW f,s

Operands: $0 \le f \le 255$
$s \in [0,1]$

Operation:
If [WREG<3:0> >9] .OR. [DC = 1] then
  WREG<3:0> + 6 → f<3:0>, s<3:0>;
else
  WREG<3:0> → f<3:0>, s<3:0>;

If [WREG<7:4> >9] .OR. [C = 1] then
  WREG<7:4> + 6 → f<7:4>, s<7:4>
else
  WREG<7:4> → f<7:4>, s<7:4>

Status Affected: C

Encoding:

0010	111s	ffff	ffff

Description: DAW adjusts the eight bit value in WREG resulting from the earlier addition of two variables (each in packed BCD format) and produces a correct packed BCD result.

s = 0: Result is placed in Data memory location 'f' and WREG.

s = 1: Result is placed in Data memory location 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'f' and other specified register

Example1:

```
DAW   REG1, 0
```

Before Instruction
WREG = 0xA5
REG1 = ??
C = 0
DC = 0

After Instruction
WREG = 0x05
REG1 = 0x05
C = 1
DC = 0

Example 2:

Before Instruction
WREG = 0xCE
REG1 = ??
C = 0
DC = 0

After Instruction
WREG = 0x24
REG1 = 0x24
C = 1
DC = 0

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (f) – 1 → (dest)

Status Affected: OV, C, DC, Z

Encoding:

0000	011d	ffff	ffff

Description: Decrement register 'f'. If 'd' is 0 the result is stored in WREG. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example:
```
DECF    CNT,   1
```
Before Instruction
CNT = 0x01
Z = 0

After Instruction
CNT = 0x00
Z = 1

DECFSZ **Decrement f, skip if 0**

Syntax: [*label*] DECFSZ f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (f) – 1 → (dest);
skip if result = 0

Status Affected: None

Encoding:

0001	011d	ffff	ffff

Description: The contents of register 'f' are decremented. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.
If the result is 0, the next instruction, which is already fetched, is discarded, and an NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example:
```
HERE    DECFSZ  CNT, 1
        GOTO    LOOP
CONTINUE
```
Before Instruction
PC = Address (HERE)

After Instruction
CNT = CNT - 1
If CNT = 0;
PC = Address (CONTINUE)
If CNT ≠ 0;
PC = Address (HERE+1)

Applicable Devices	42	R42	42A	43	R43	44

17.1 DC CHARACTERISTICS: PIC17C42-16 (Commercial, Industrial) PIC17C42-25 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.5	–	5.5	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060*	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D012			–	11	24 *	mA	FOSC = 16 MHz
D013			–	19	38	mA	FOSC = 25 MHz
D014			–	95	150	µA	FOSC = 32 kHz WDT enabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads need to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, The current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency on the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

Applicable Devices	42	R42	42A	43	R43	44

19.0 PIC17CR42/42A/43/R43/44 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125˚C

Storage temperature ..... -65˚C to +150˚C

Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... -0.6V to +14V

Voltage on RA2 and RA3 with respect to V_{SS} ..... -0.6V to +14V

Voltage on all other pins with respect to V_{SS} ..... -0.6V to V_{DD} + 0.6V

Total power dissipation (Note 1) 1.0W

Maximum current out of V_{SS} pin(s) - total ..... 250 mA

Maximum current into V_{DD} pin(s) - total ..... 200 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Maximum output current sunk by any I/O pin (except RA2 and RA3) ..... 35 mA

Maximum output current sunk by RA2 or RA3 pins ..... 60 mA

Maximum output current sourced by any I/O pin ..... 20 mA

Maximum current sunk by PORTA and PORTB (combined) ..... 150 mA

Maximum current sourced by PORTA and PORTB (combined) ..... 100 mA

Maximum current sunk by PORTC, PORTD and PORTE (combined) ..... 150 mA

Maximum current sourced by PORTC, PORTD and PORTE (combined) ..... 100 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Applicable Devices	42	R42	42A	43	R43	44

19.1 DC CHARACTERISTICS: PIC17CR42/42A/43/R43/44-16 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-25 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-33 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.5	–	6.0	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060 *	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D012			–	11	24 *	mA	FOSC = 16 MHz
D013			–	19	38	mA	FOSC = 25 MHz
D015			–	25	50	mA	FOSC = 33 MHz
D014			–	95	150	µA	FOSC = 32 kHz, WDT enabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

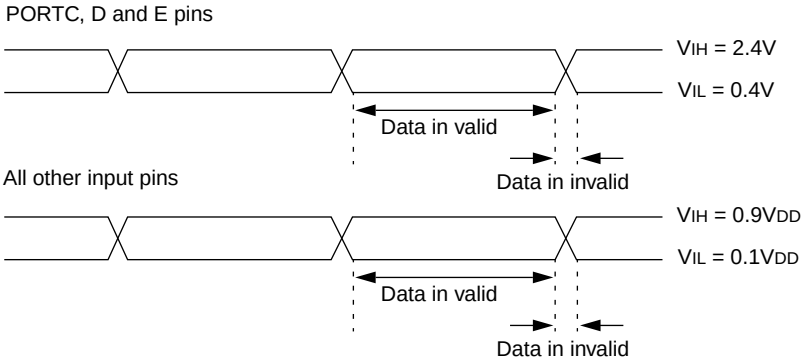
4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

Applicable Devices	42	R42	42A	43	R43	44

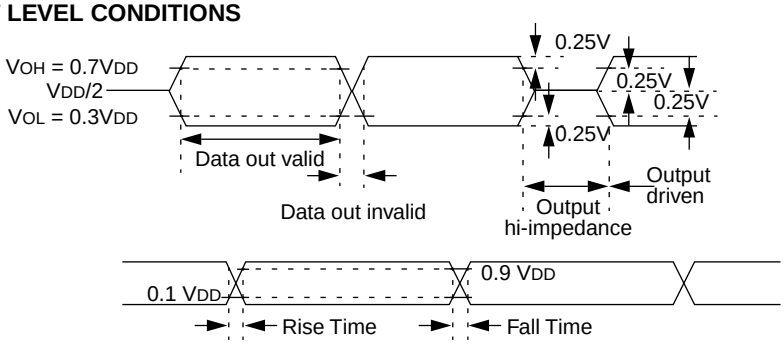
FIGURE 19-1: PARAMETER MEASUREMENT INFORMATION

All timings are measure between high and low measurement points as indicated in the figures below.

INPUT LEVEL CONDITIONS

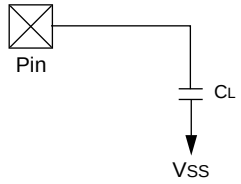


OUTPUT LEVEL CONDITIONS



LOAD CONDITIONS

Load Condition 1



50 pF ≤ CL

Applicable Devices	42	R42	42A	43	R43	44

19.5 Timing Diagrams and Specifications

FIGURE 19-2: EXTERNAL CLOCK TIMING

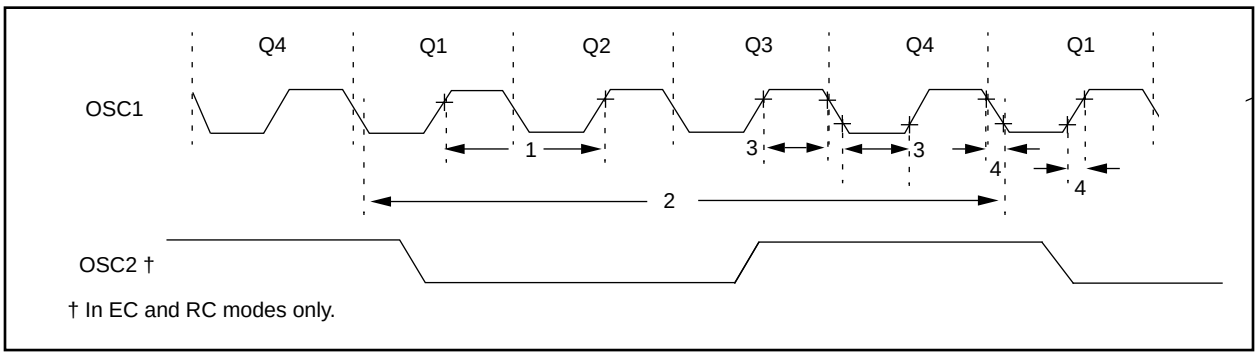


TABLE 19-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	8	MHz	EC osc mode - 08 devices (8 MHz devices)
			DC	—	16	MHz	- 16 devices (16 MHz devices)
			DC	—	25	MHz	- 25 devices (25 MHz devices)
			DC	—	33	MHz	- 33 devices (33 MHz devices)
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			1	—	8	MHz	XT osc mode - 08 devices (8 MHz devices)
			1	—	16	MHz	- 16 devices (16 MHz devices)
			1	—	25	MHz	- 25 devices (25 MHz devices)
			1	—	33	MHz	- 33 devices (33 MHz devices)
			DC	—	2	MHz	LF osc mode
1	Tosc	**External CLKIN Period (Note 1)**	125	—	—	ns	EC osc mode - 08 devices (8 MHz devices)
			62.5	—	—	ns	- 16 devices (16 MHz devices)
			40	—	—	ns	- 25 devices (25 MHz devices)
			30.3	—	—	ns	- 33 devices (33 MHz devices)
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			125	—	1,000	ns	XT osc mode - 08 devices (8 MHz devices)
			62.5	—	1,000	ns	- 16 devices (16 MHz devices)
			40	—	1,000	ns	- 25 devices (25 MHz devices)
			30.3	—	1,000	ns	- 33 devices (33 MHz devices)
			500	—	—	ns	LF osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	121.2	4/Fosc	DC	ns	
3	TosL, TosH	**Clock in (OSC1) high or low time**	10 ‡	—	—	ns	EC oscillator
4	TosR, TosF	**Clock in (OSC1) rise or fall time**	—	—	5 ‡	ns	EC oscillator

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-7: TYPICAL IDD vs. FREQUENCY (EXTERNAL CLOCK 25°C)

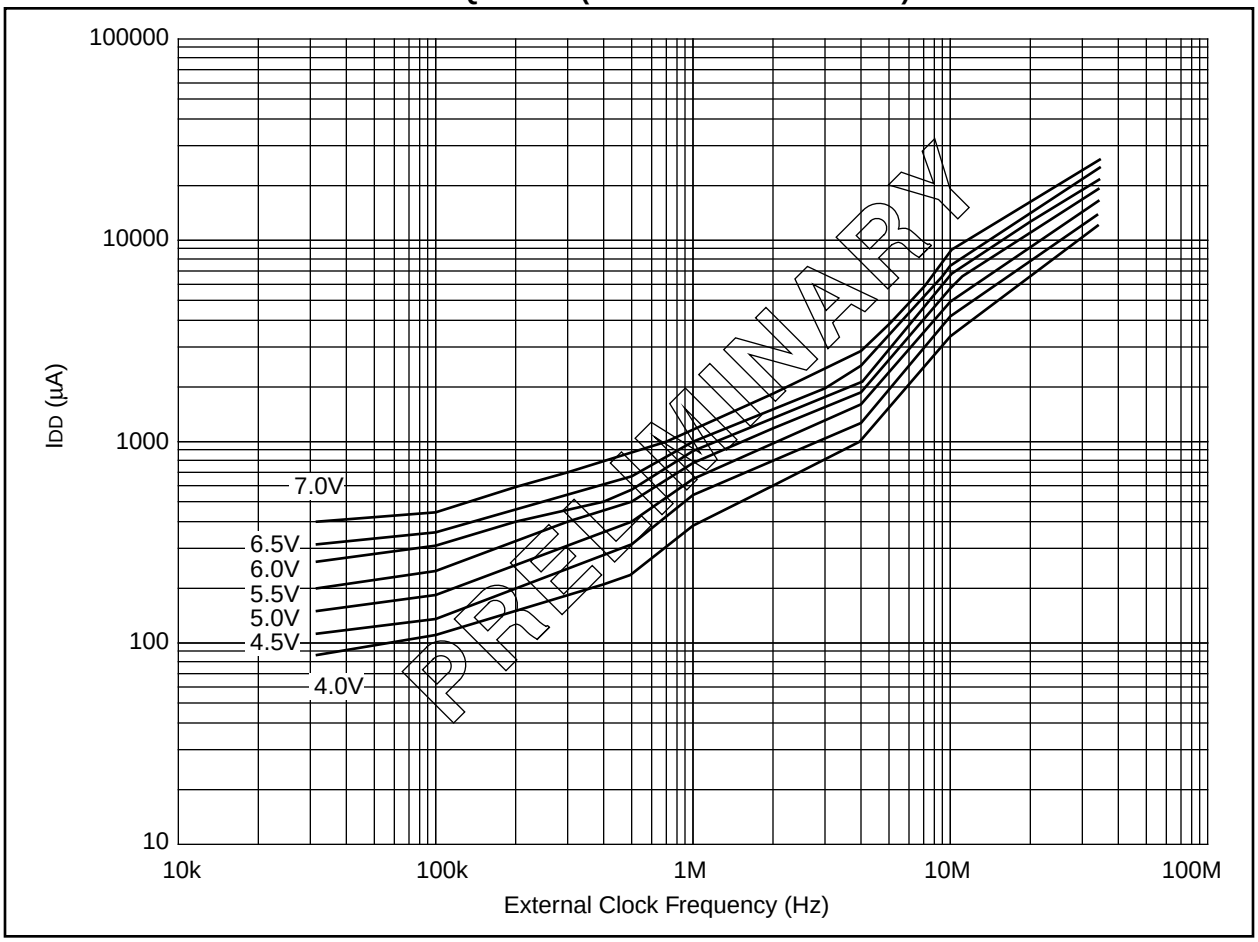
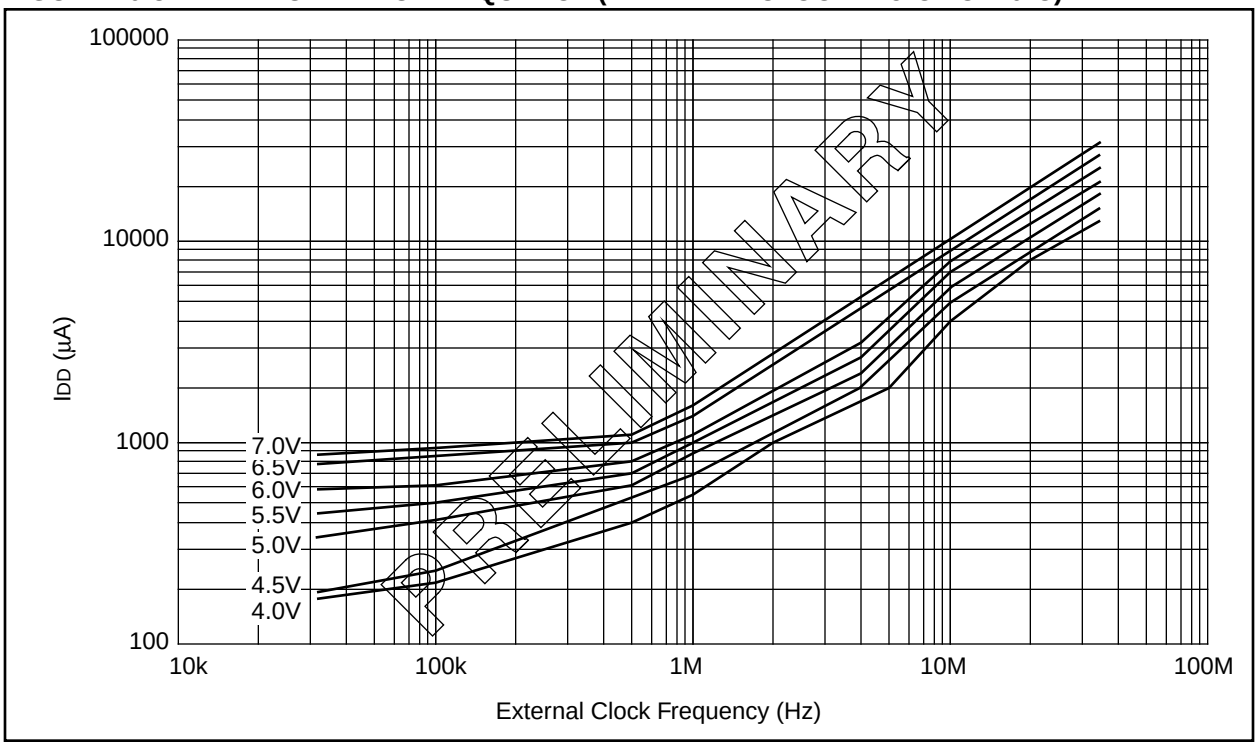


FIGURE 20-8: MAXIMUM IDD vs. FREQUENCY (EXTERNAL CLOCK 125°C TO -40°C)



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-11: TYPICAL IPD vs. VDD WATCHDOG ENABLED 25°C

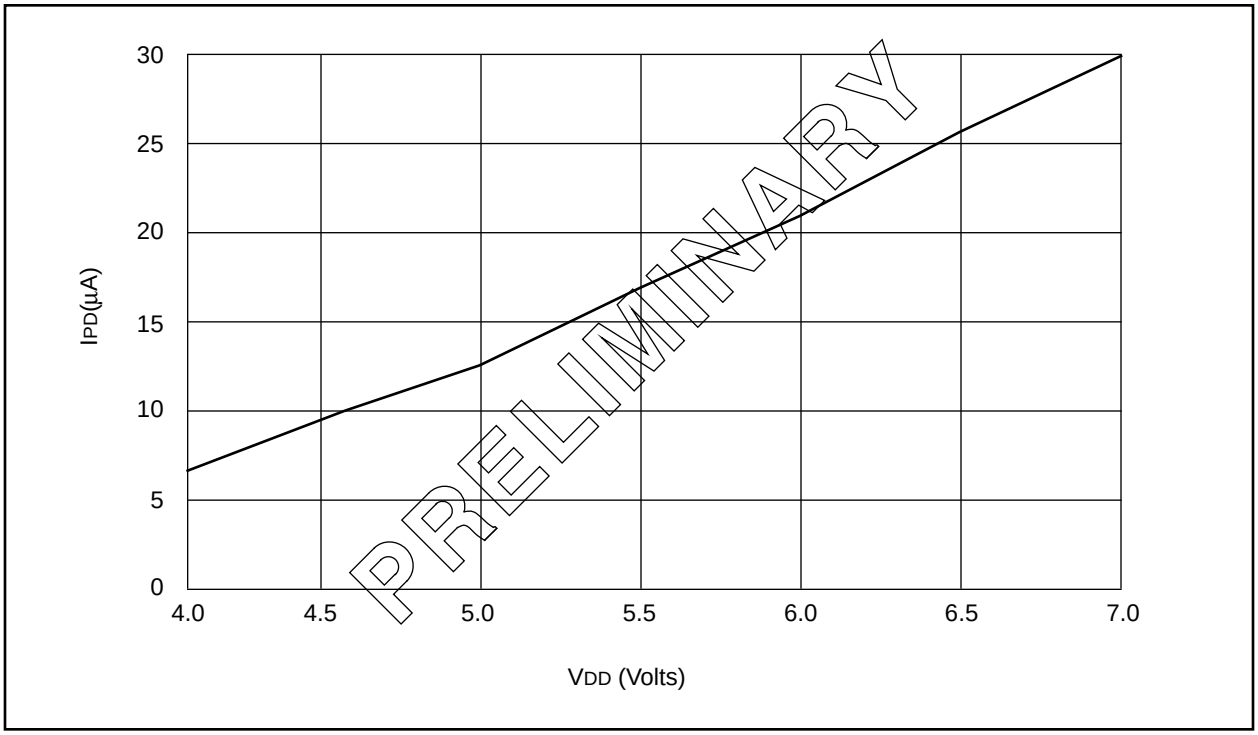
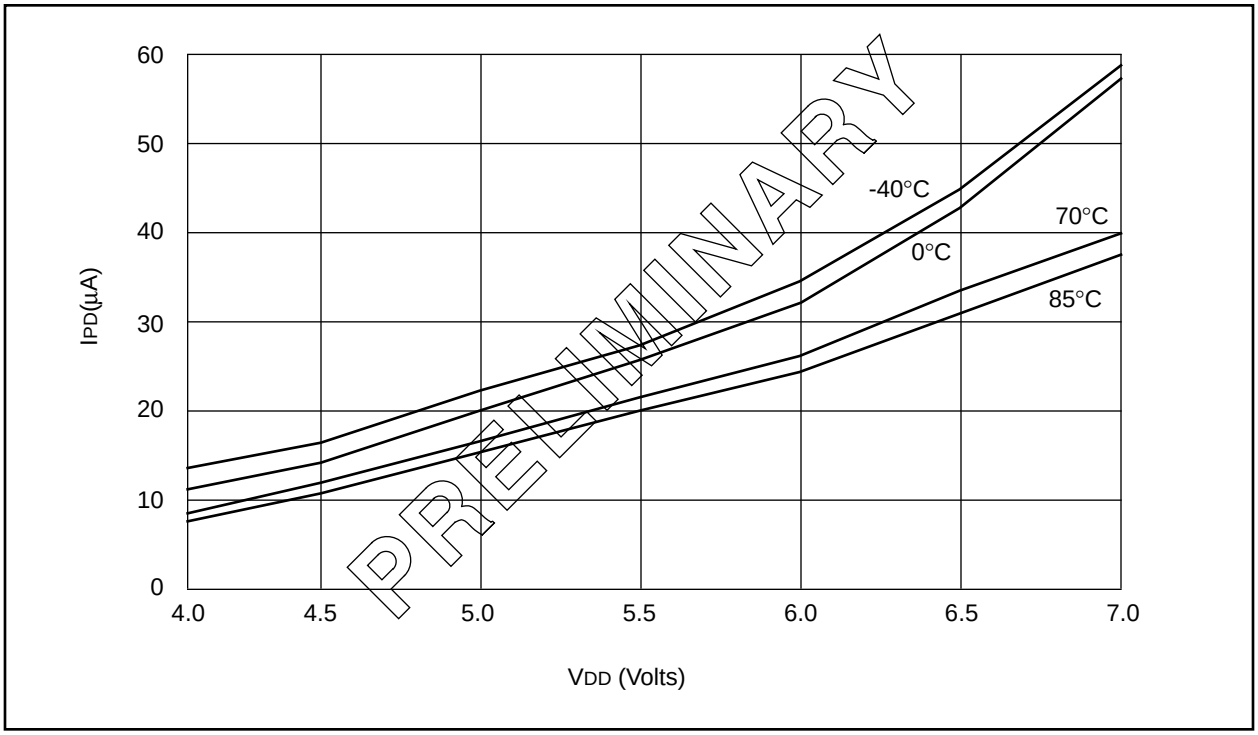
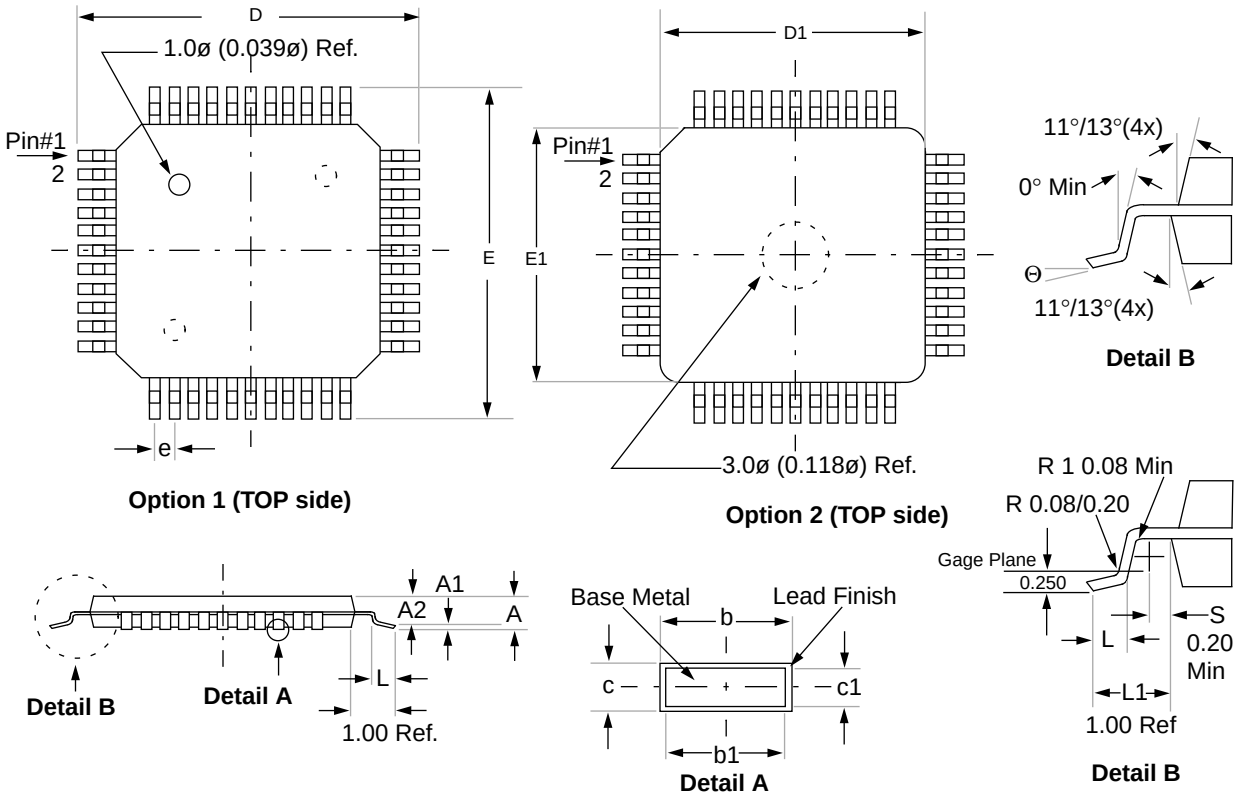


FIGURE 20-12: MAXIMUM IPD vs. VDD WATCHDOG ENABLED



21.5 44-Lead Plastic Surface Mount (TQFP 10x10 mm Body 1.0/0.10 mm Lead Form)



Package Group: Plastic TQFP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
A	1.00	1.20		0.039	0.047	
A1	0.05	0.15		0.002	0.006	
A2	0.95	1.05		0.037	0.041	
D	11.75	12.25		0.463	0.482	
D1	9.90	10.10		0.390	0.398	
E	11.75	12.25		0.463	0.482	
E1	9.90	10.10		0.390	0.398	
L	0.45	0.75		0.018	0.030	
e	0.80 BSC			0.031 BSC		
b	0.30	0.45		0.012	0.018	
b1	0.30	0.40		0.012	0.016	
c	0.09	0.20		0.004	0.008	
c1	0.09	0.16		0.004	0.006	
N	44	44		44	44	
Θ	0°	7°		0°	7°	

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25m/m (0.010”) per side. D1 and E1 dimensions including mold mismatch.

2: Dimension “b” does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08m/m (0.003”)max.

3: This outline conforms to JEDEC MS-026.

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